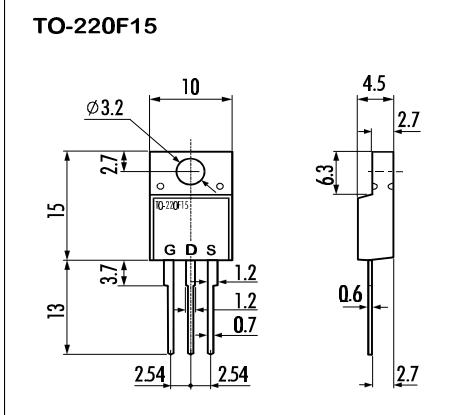


> Features

- High Speed Switching
- Low On-Resistance
- No Secondary Breakdown
- Low Driving Power
- High Voltage
- $V_{GS} = \pm 30V$ Guarantee
- Avalanche Proof

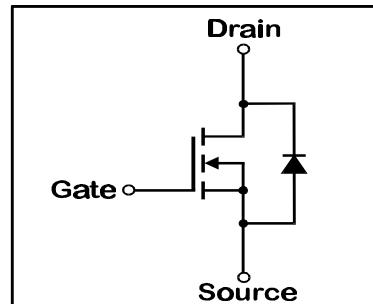
> Applications

- Switching Regulators
- UPS
- DC-DC converters
- General Purpose Power Amplifier

> Outline Drawing

> Maximum Ratings and Characteristics

- Absolute Maximum Ratings ($T_C=25^\circ C$), unless otherwise specified

Item	Symbol	Rating	Unit
Drain-Source-Voltage	V_{DS}	200	V
Drain-Gate-Voltage($R_{GS}=20\text{ k}\Omega$)	V_{DGR}	200	V
Continuous Drain Current	I_D	10	A
Pulsed Drain Current	$I_{D(\text{puls})}$	40	A
Gate-Source-Voltage	V_{GS}	± 30	V
Max. Power Dissipation	P_D	30	W
Operating and Storage Temperature Range	T_{ch}	150	$^\circ C$
	T_{stg}	-55 ~ +150	$^\circ C$

> Equivalent Circuit


- Electrical Characteristics ($T_C=25^\circ C$), unless otherwise specified

Item	Symbol	Test conditions	Min.	Typ.	Max.	Unit
Drain-Source Breakdown-Voltage	$V_{(BR)DSS}$	$I_D=1\text{ mA}$ $V_{GS}=0\text{ V}$	200			V
Gate Threshold Voltage	$V_{GS(\text{th})}$	$I_D=1\text{ mA}$ $V_{DS}=V_{GS}$	2,5	3,0	3,5	V
Zero Gate Voltage Drain Current	I_{DSS}	$V_{DS}=200\text{ V}$ $T_{ch}=25^\circ C$ $V_{GS}=0\text{ V}$ $T_{ch}=125^\circ C$		10	500	μA
Gate Source Leakage Current	I_{GSS}	$V_{GS}=\pm 30\text{ V}$ $V_{DS}=0\text{ V}$		10	100	nA
Drain Source On-State Resistance	$R_{DS(on)}$	$I_D=5\text{ A}$ $V_{GS}=10\text{ V}$		0,35	0,4	Ω
Forward Transconductance	g_{fs}	$I_D=5\text{ A}$ $V_{DS}=25\text{ V}$	2,0	4,5		S
Input Capacitance	C_{iss}	$V_{DS}=25\text{ V}$		500	750	pF
Output Capacitance	C_{oss}	$V_{GS}=0\text{ V}$		110	170	pF
Reverse Transfer Capacitance	C_{rss}	$f=1\text{ MHz}$		50	80	pF
Turn-On-Time t_{on} ($t_{on}=t_{d(on)}+t_r$)	$t_{d(on)}$	$V_{CC}=150\text{ V}$		10	20	ns
	t_r	$I_D=10\text{ A}$		30	50	ns
Turn-Off-Time t_{off} ($t_{off}=t_{d(off)}+t_f$)	$t_{d(off)}$	$V_{GS}=10\text{ V}$		30	50	ns
	t_f	$R_{GS}=10\text{ }\Omega$		20	30	ns
Avalanche Capability	I_{AV}	$L=100\mu\text{H}$ $T_{ch}=25^\circ C$	10,0			A
Diode Forward On-Voltage	V_{SD}	$I_F=2xI_{DR}$ $V_{GS}=0\text{ V}$ $T_{ch}=25^\circ C$		1,15	1,8	V
Reverse Recovery Time	t_{rr}	$I_F=I_{DR}$ $V_{GS}=0\text{ V}$		130		ns
Reverse Recovery Charge	Q_{rr}	$-dI_F/dt=100\text{ A}/\mu\text{s}$ $T_{ch}=25^\circ C$		750		μC

- Thermal Characteristics

Item	Symbol	Test conditions	Min.	Typ.	Max.	Unit
Thermal Resistance	$R_{th(ch-a)}$	channel to air			62,5	$^\circ\text{C/W}$
	$R_{th(ch-c)}$	channel to case			4,17	$^\circ\text{C/W}$

N-channel MOS-FET	
200V	0,4Ω

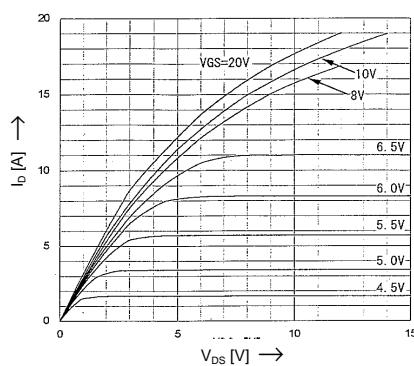
2SK2520-01MR

FAP-II Series

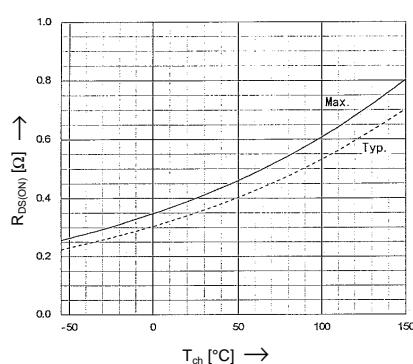
FUJI
ELECTRIC

> Characteristics

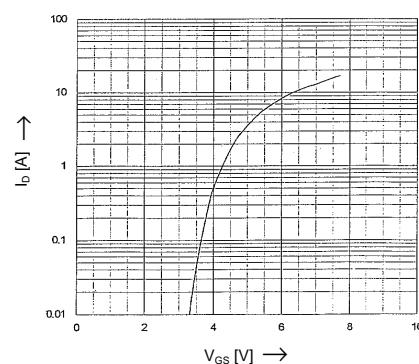
Typical Output Characteristics
 $I_D=f(V_{DS})$; 80μs pulse test; $T_C=25^\circ\text{C}$



Drain-Source On-State Resistance
 $R_{DS(on)}=f(T_{ch})$; $I_D=5\text{A}$; $V_{GS}=10\text{V}$

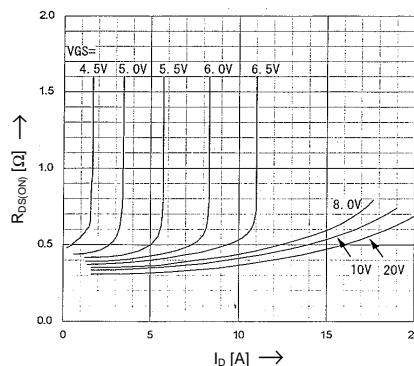


Typical Transfer Characteristics
 $I_D=f(V_{GS})$; 80μs pulse test; $V_{DS}=25\text{V}$; $T_C=25^\circ\text{C}$



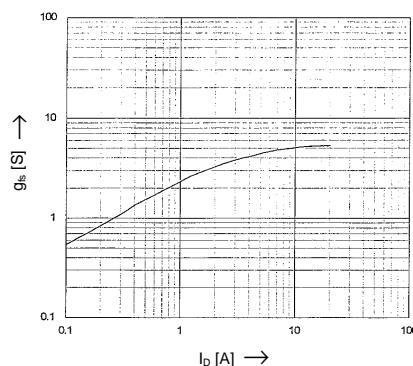
Typical Drain-Source On-State-Resistance

$R_{DS(on)}=f(I_D)$; 80μs pulse test; $T_C=25^\circ\text{C}$



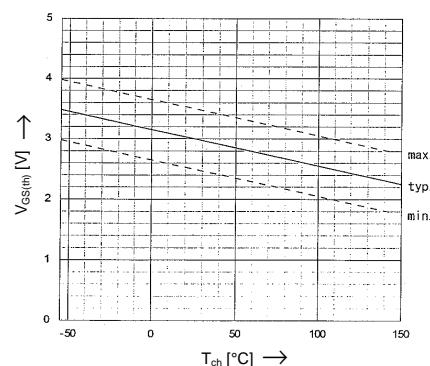
Typical Transconductance

$g_m=f(I_D)$; 80μs pulse test; $V_{DS}=25\text{V}$; $T_C=25^\circ\text{C}$



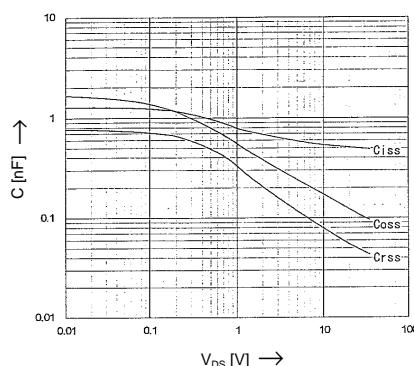
Gate Threshold Voltage vs. T_{ch}

$V_{GS(th)}=f(T_{ch})$; $I_D=1\text{mA}$; $V_{DS}=V_{GS}$



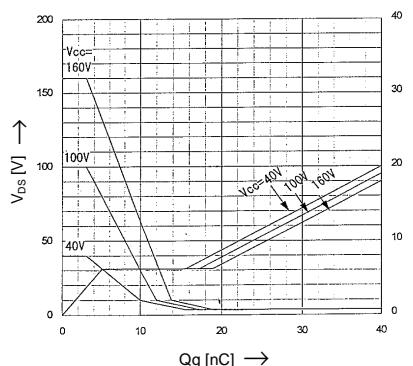
Typical Capacitances

$C=f(V_{DS})$; $V_{GS}=0\text{V}$; $f=1\text{MHz}$



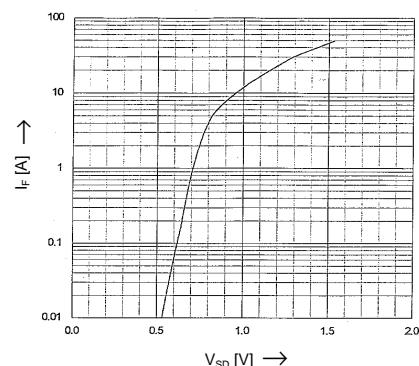
Typical Gate Charge Characteristics

$V_{GS}=f(Q_g)$; $I_D=10\text{A}$



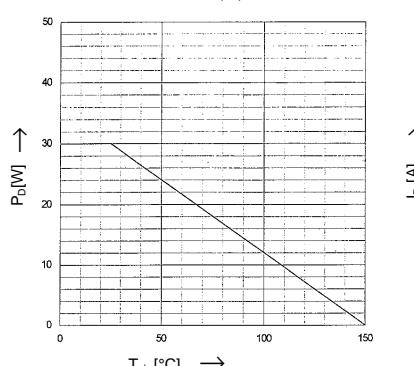
Forward Characteristics of Reverse Diode

$I_F=f(V_{SD})$; 80μs pulse test $T_C=25^\circ\text{C}$; $V_{GS}=0\text{V}$



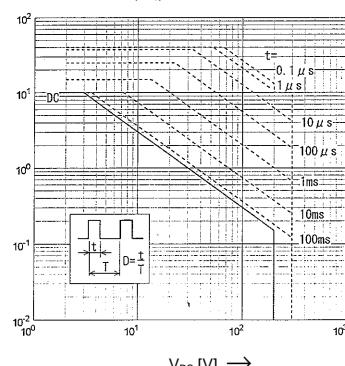
Power Dissipation

$P_D=f(T_C)$



Safe Operation Area

$I_D=f(V_{DS})$; $D=0.01$, $T_C=25^\circ\text{C}$



Transient Thermal impedance

$Z_{th(ch-c)}=f(t)$ parameter: $D=t/T$

